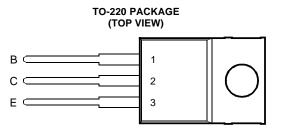
JUNE 1973 - REVISED MARCH 1997

- Designed for Complementary Use with the BD540 Series
- 45 W at 25°C Case Temperature
- 5 A Continuous Collector Current
- Up to 120 V V_{CEO} rating



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	BD539		40	
	BD539A		60	
Collector-base voltage	BD539B	V _{CBO}	80	V
	BD539C		100	
	BD539D		120	
	BD539		40	
Collector-emitter voltage (see Note 1)	BD539A		60	
	BD539B	V _{CEO}	80	V
	BD539C		100	
	BD539D		120	
Emitter-base voltage	V _{EBO}	5	V	
Continuous collector current			5	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			45	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			2	W
Operating free air temperature range			-65 to +150	°C
Operating junction temperature range			-65 to +150	°C
Storage temperature range			-65 to +150	°C
Lead temperature 3.2 mm from case for 10 seconds			260	°C

NOTES: 1. These values apply when the base-emitter diode is open circuited.

2. Derate linearly to 150°C case temperature at the rate of 0.36 W/°C.

3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



JUNE 1973 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature

PARAMETER			TEST CONDITI	ONS	MIN	ТҮР	MAX	UNIT
				BD539 BD539A	40 60	-		
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	BD539B	80			V
		(see Note 4)		BD539C	100			
				BD539D	120			
	Collector-emitter cut-off current	V _{CE} = 40 V	$V_{BE} = 0$	BD539			0.2	
		V _{CE} = 60 V	$V_{BE} = 0$	BD539A			0.2	
I _{CES}		V _{CE} = 80 V	$V_{BE} = 0$	BD539B			0.2	mA
		V _{CE} = 100 V	$V_{BE} = 0$	BD539C			0.2	
		V _{CE} = 120 V	$V_{BE} = 0$	BD539D			0.2	
	Collector cut-off current	V _{CE} = 30 V	I _B = 0	BD539/539A			0.3	
I _{CEO}		V _{CE} = 60 V	$I_B = 0$	BD539B/539C			0.3	mA
		V _{CE} = 90 V	$I_B = 0$	BD539D			0.3	
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0				1	mA
	Forward current transfer ratio	$V_{CE} = 4 V$	I _C = 0.5 A		40			
h _{FE}		$V_{CE} = 4 V$	I _C = 1 A	(see Notes 4 and 5)	30			
		$V_{CE} = 4 V$	I _C = 3 A		12			
	Collector-emitter saturation voltage	I _B = 125 mA	I _C = 1 A				0.25	
V _{CE(sat)}		I _B = 375 mA	I _C = 3 A	(see Notes 4 and 5)			0.8	V
		I _B = 1 A	I _C = 5 A				1.5	
V _{BE(on)}	Base-emitter voltage	V _{CE} = 4 V	I _C = 3 A	(see Notes 4 and 5)			1.25	V
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 0.5 A	f = 1 kHz	20			
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 0.5 A	f = 1 MHz	3			

NOTES: 4. These parameters must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2%.
5. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

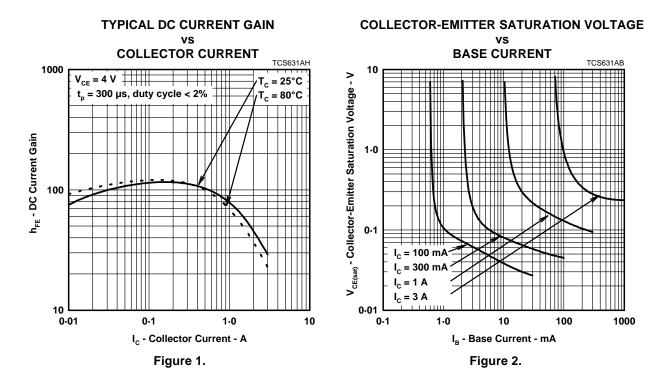
PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			2.78	°C/W
R_{\thetaJA}	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

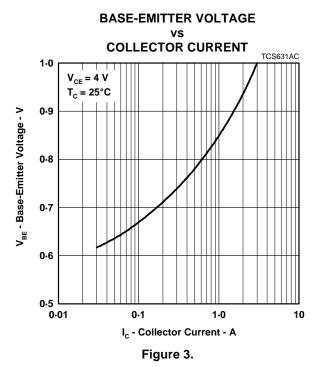
	PARAMETER	TEST CONDITIONS [†]			MIN	TYP	MAX	UNIT
t _{on}	Turn-on time	I _C = 1 A	$I_{B(on)} = 0.1 \text{ A}$	I _{B(off)} = -0.1 A		0.5		μs
t _{off}	Turn-off time	$V_{BE(off)} = -4.3 V$	$R_L = 30 \Omega$	t_p = 20 µs, dc \leq 2%		2		μs

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

JUNE 1973 - REVISED MARCH 1997

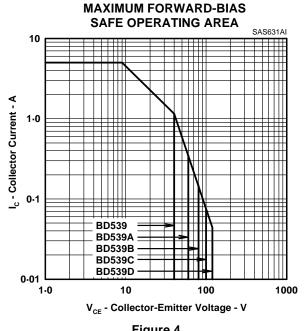


TYPICAL CHARACTERISTICS





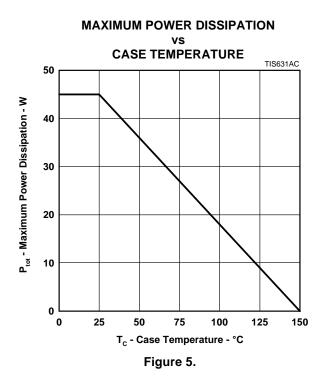
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MAXIMUM SAFE OPERATING REGIONS







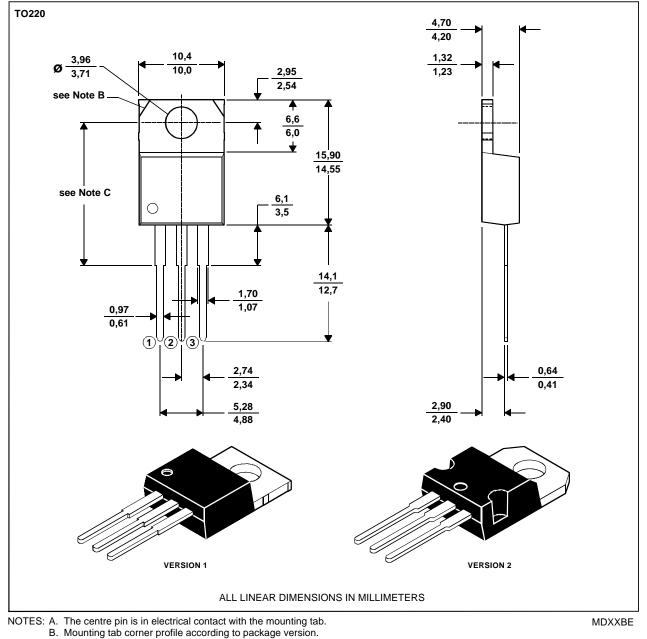
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.



JUNE 1973 - REVISED MARCH 1997

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